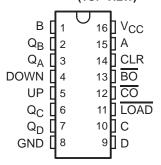
- DECEMBER 1982 - REVISED OCTOBER 200

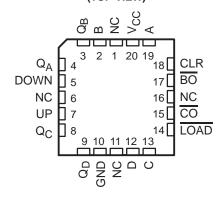
- Wide Operating Voltage Range of 2 V to 6 V
- **Outputs Can Drive Up To 10 LSTTL Loads**
- Low Power Consumption, 80-µA Max ICC
- Typical $t_{nd} = 20 \text{ ns}$
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 µA Max

SN54HC193 . . . J OR W PACKAGE SN74HC193...D, N, NS, OR PW PACKAGE (TOP VIEW)



- **Look-Ahead Circuitry Enhances Cascaded** Counters
- **Fully Synchronous in Count Modes**
- Parallel Asynchronous Load for Modulo-N **Count Lengths**
- **Asynchronous Clear**

SN54HC193 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

'HC193 devices 4-bit synchronous, reversible, up/down binary counters. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincidentally with each other when so instructed by the steering logic. This mode of operation eliminates the output counting spikes normally associated with asynchronous (ripple-clock) counters.

ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
	PDIP – N	Tube of 25	SN74HC193N	SN74HC193N		
		Tube of 40	SN74HC193D			
	SOIC - D	Reel of 2500	SN74HC193DR	HC193		
4000 1- 0500		Reel of 250	SN74HC193DT			
-40°C to 85°C	SOP - NS	- NS Reel of 2000 SN74HC193NSR		HC193		
		Tube of 90	SN74HC193PW			
	TSSOP - PW	Reel of 2000	SN74HC193PWR	HC193		
		Reel of 250	SN74HC193PWT			
	CDIP – J	Tube of 25	SNJ54HC193J	SNJ54HC193J		
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HC193W	SNJ54HC193W		
	LCCC – FK	Tube of 55	SNJ54HC193FK	SNJ54HC193FK		

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SN54HC193, SN74HC193 4-BIT SYNCHRONOUS UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR)

SCLS122D - DECEMBER 1982 - REVISED OCTOBER 2003

description/ordering information (continued)

The outputs of the four flip-flops are triggered on a low-to-high-level transition of either count (clock) input (UP or DOWN). The direction of counting is determined by which count input is pulsed while the other count input is high.

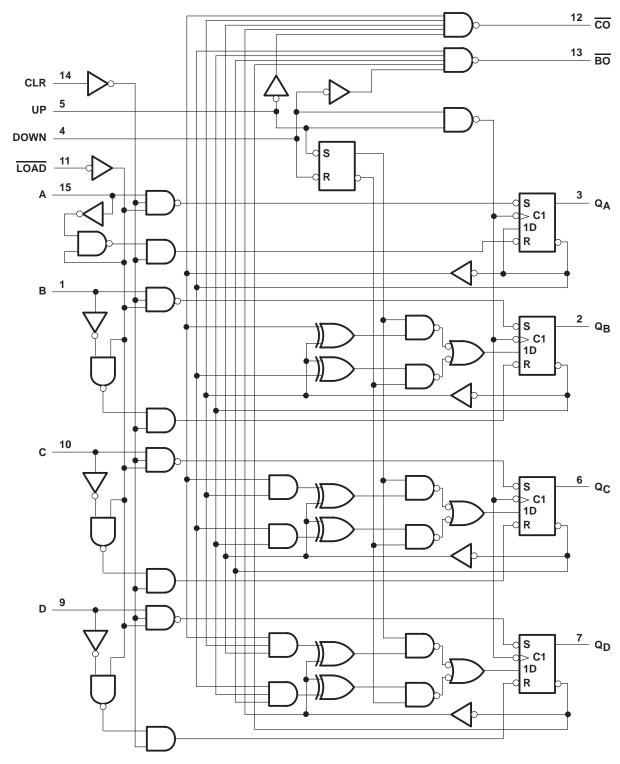
All four counters are fully programmable; that is, each output may be preset to either level by placing a low on the load (LOAD) input and entering the desired data at the data inputs. The output changes to agree with the data inputs independently of the count pulses. This feature allows the counters to be used as modulo-N dividers simply by modifying the count length with the preset inputs.

A clear (CLR) input has been provided that forces all outputs to the low level when a high level is applied. The clear function is independent of the count and LOAD inputs.

These counters were designed to be cascaded without the need for external circuitry. The borrow (\overline{BO}) output produces a low-level pulse while the count is zero (all outputs low) and DOWN is low. Similarly, the carry (\overline{CO}) output produces a low-level pulse while the count is maximum (9 or 15), and UP is low. The counters then can be cascaded easily by feeding \overline{BO} and \overline{CO} to DOWN and UP, respectively, of the succeeding counter.



logic diagram (positive logic)



Pin numbers shown are for the D, J, N, NS, PW, and W packages.

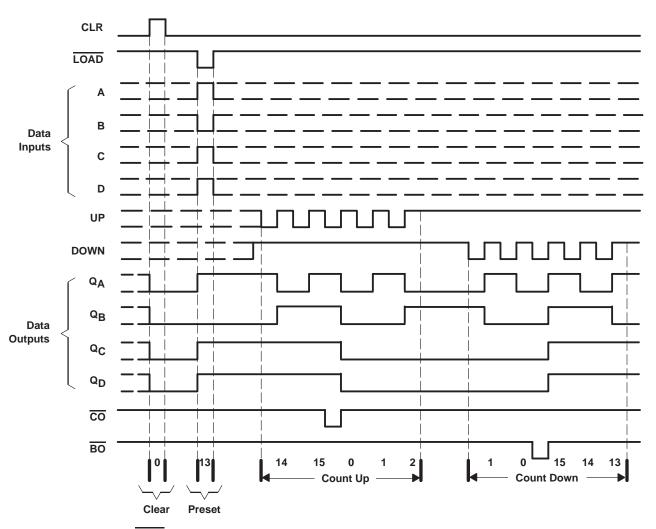


SCLS122D - DECEMBER 1982 - REVISED OCTOBER 2003

typical clear, load, and count sequence

The following sequence is illustrated below:

- 1. Clear outputs to 0
- 2. Load (preset) to binary 13
- 3. Count up to 14, 15, carry, 0, 1, and 2
- 4. Count down to 1, 0, borrow, 15, 14, and 13



NOTES: A. CLR overrides LOAD, data, and count inputs.

B. When counting up, count-down input must be high; when counting down, count-up input must be high.



SN54HC193, SN74HC193 4-BIT SYNCHRONOUS UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR) SCLS122D - DECEMBER 1982 - REVISED OCTOBER 2003

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}		0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see	ee Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CO}$	C) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	-	±25 mA
Continuous current through V _{CC} or GND		±50 mA
Package thermal impedance, θ_{JA} (see Note 2):	: D package	73°C/W
	N package	67°C/W
	NS package	64°C/W
	PW package	108°C/W
Storage temperature range, T _{Stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN	154HC19)3	SN	174HC19	3	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
ViH	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V
		VCC = 6 V	4.2			4.2			
		V _{CC} = 2 V			0.5			0.5	
VIL	Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	V
		V _{CC} = 6 V			1.8			1.8	
VI	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V			1000			1000	
Δt/Δv‡	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns
		V _{CC} = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

[‡] If this device is used in the threshold region (from V_{IL}max = 0.5 V to V_{IH}min = 1.5 V), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at t_t = 1000 ns and V_{CC} = 2 V does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.

SN54HC193, SN74HC193 4-BIT SYNCHRONOUS UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR) SCLS122D - DECEMBER 1982 - REVISED OCTOBER 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	7507.00	NIDITIONS	.,	Т	A = 25°C	;	SN54H	C193	SN74H	IC193	
PARAMETER	I IEST CC	ONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1		0.1		0.1	
VOL	VI = VIH or VIL		6 V		0.001	0.1		0.1		0.1	V
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0	·	6 V		±0.1	±100		±1000		±1000	nA
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci		_	2 V to 6 V		3	10		10		10	pF

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			Ι.,	T _A =	25°C	SN54H	IC193	SN74H	C193	
			VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		4.2		2.8		3.3	
fclock	Clock frequency		4.5 V		21		14		17	MHz
			6 V		24		16		19	
			2 V	120		180		150		
		CLR high	4.5 V	24		36		30		
			6 V	21		31		26		
			2 V	120		180		150		
t_{W}	Pulse duration	LOAD low	4.5 V	24		36		30		ns
			6 V	21		31		26		
			2 V	120		180		150		
		UP or DOWN high or low	4.5 V	24		36		30		
			6 V	21		31		26		
			2 V	110		165		140		
		Data before LOAD inactive	4.5 V	22		33		28		
			6 V	19		28		24		
			2 V	110		165		140		
t _{su}	Setup time	CLR inactive before UP↑ or DOWN↑	4.5 V	22		33		28		ns
			6 V	19		28		24		
			2 V	110		165		140		
		LOAD inactive before UP↑ or DOWN↑	4.5 V	22		33		28		
			6 V	19		28		24		
			2 V	5		5		5		_
th	Hold time	Data after LOAD inactive	4.5 V	5		5		5		ns
			6 V	5		5		5		



SN54HC193, SN74HC193 4-BIT SYNCHRONOUS UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR) SCLS122D - DECEMBER 1982 - REVISED OCTOBER 2003

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

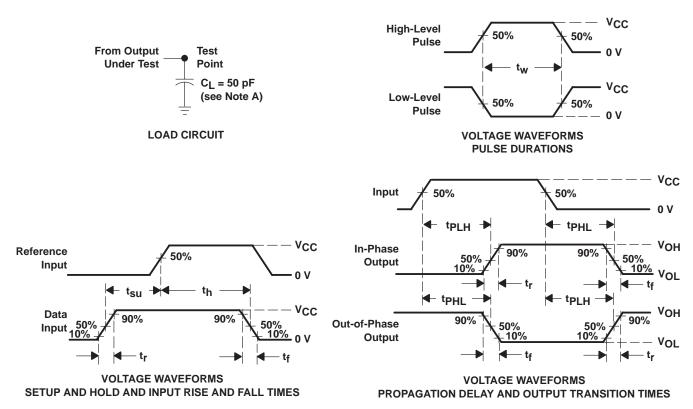
24244555	FROM	то	,,	T,	Δ = 25°C	;	SN54F	IC193	SN74F	IC193	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	4.2	8		2.8		3.3		
f _{max}			4.5 V	21	55		14		17		MHz
			6 V	24	60		16		19		
			2 V		75	165		250		205	
	UP	CO	4.5 V		24	33		50		41	
			6 V		20	28		43		35	
			2 V		75	165		250		205	
	DOWN	BO	4.5 V		24	33		50		41	
			6 V		20	28		43		35	
^t pd			2 V		190	250		375		315	ns
	UP or DOWN	Any Q	4.5 V		40	50		75		63	
			6 V		35	43		64		54	
			2 V		190	260		390		325	
	LOAD	Any Q	4.5 V		40	52		78		65	
			6 V		35	44		66		55	
			2 V		170	240		360		300	
tPHL	CLR	Any Q	4.5 V		36	48		72		60	ns
			6 V		31	41		61		51	
			2 V		38	75		110		95	
t _t		Any	4.5 V		8	15		22		19	ns
			6 V		6	13		19		16	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load	50	pF

SCLS122D - DECEMBER 1982 - REVISED OCTOBER 2003

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 6 \ ns$, $t_f = 6 \ ns$.
- C. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



www.ti.com 14-Aug-2021

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8772401EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8772401EA SNJ54HC193J	Samples
SN54HC193J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54HC193J	Samples
SN74HC193D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC193	Samples
SN74HC193DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC193	Samples
SN74HC193N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC193N	Samples
SN74HC193NE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC193N	Samples
SN74HC193NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC193	Samples
SN74HC193PW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC193	Samples
SN74HC193PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC193	Samples
SNJ54HC193J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8772401EA SNJ54HC193J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽²⁾ **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

PACKAGE OPTION ADDENDUM

www.ti.com 14-Aug-2021

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54HC193, SN74HC193:

Catalog: SN74HC193

Automotive: SN74HC193-Q1, SN74HC193-Q1

Military: SN54HC193

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

Military - QML certified for Military and Defense Applications

www.ti.com 5-Jan-2022

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device Device	Package Type	Package Drawing		SPQ	Reel Diameter	Reel Width	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC193DR	SOIC	D	16	2500	(mm) 330.0	W1 (mm) 16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC193NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74HC193PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

www.ti.com 5-Jan-2022



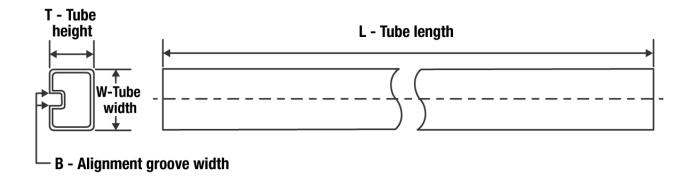
*All dimensions are nominal

7 til dillionorono di o mominar							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC193DR	SOIC	D	16	2500	340.5	336.1	32.0
SN74HC193NSR	SO	NS	16	2000	853.0	449.0	35.0
SN74HC193PWR	TSSOP	PW	16	2000	853.0	449.0	35.0

PACKAGE MATERIALS INFORMATION

www.ti.com 5-Jan-2022

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74HC193D	D	SOIC	16	40	507	8	3940	4.32
SN74HC193N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC193N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC193NE4	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC193NE4	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC193PW	PW	TSSOP	16	90	530	10.2	3600	3.5

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2022, Texas Instruments Incorporated